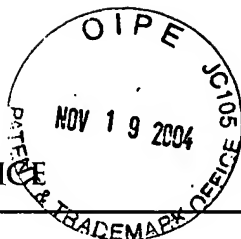




UNITED STATES
PATENT AND
TRADEMARK OFFICE
★★★★



FEBRUARY 13, 2002

PTAS

STETINA BRUNDA GARRED & BRUCKER
MARK B. GARRED
75 ENTERPRISE, STE. 250
ALISO VIEJO, CA 92656

Under Secretary of Commerce For Intellectual Property and
Director of the United States Patent and Trademark Office
Washington, DC 20231
www.uspto.gov



101925959A

UNITED STATES PATENT AND TRADEMARK OFFICE
NOTICE OF RECORDATION OF ASSIGNMENT DOCUMENT

THE ENCLOSED DOCUMENT HAS BEEN RECORDED BY THE ASSIGNMENT DIVISION OF THE U.S. PATENT AND TRADEMARK OFFICE. A COMPLETE MICROFILM COPY IS AVAILABLE AT THE ASSIGNMENT SEARCH ROOM ON THE REEL AND FRAME NUMBER REFERENCED BELOW.

PLEASE REVIEW ALL INFORMATION CONTAINED ON THIS NOTICE. THE INFORMATION CONTAINED ON THIS RECORDATION NOTICE REFLECTS THE DATA PRESENT IN THE PATENT AND TRADEMARK ASSIGNMENT SYSTEM. IF YOU SHOULD FIND ANY ERRORS OR HAVE QUESTIONS CONCERNING THIS NOTICE, YOU MAY CONTACT THE EMPLOYEE WHOSE NAME APPEARS ON THIS NOTICE AT 703-308-9723. PLEASE SEND REQUEST FOR CORRECTION TO: U.S. PATENT AND TRADEMARK OFFICE, ASSIGNMENT DIVISION, BOX ASSIGNMENTS, CG-4, 1213 JEFFERSON DAVIS HWY, SUITE 320, WASHINGTON, D.C. 20231.

RECORDATION DATE: 12/14/2001

REEL/FRAME: 012386/0039

NUMBER OF PAGES: 3

BRIEF: ASSIGNMENT OF ASSIGNOR'S INTEREST (SEE DOCUMENT FOR DETAILS).

ASSIGNOR:

ROETERS, GLEN E.

DOC DATE: 12/12/2001

ASSIGNEE:

DPAC TECHNOLOGIES CORP.
7321 LINCOLN WAY
GARDEN GROVE, CALIFORNIA 92841

SERIAL NUMBER: 10016939

FILING DATE: 12/14/2001

PATENT NUMBER:

ISSUE DATE:

MARCUS KIRK, EXAMINER
ASSIGNMENT DIVISION
OFFICE OF PUBLIC RECORDS

WRO 12-14-01

12-27-2001



101925959

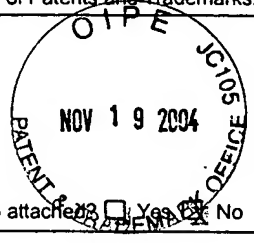
Form PTO-1595
(Rev. 03/01)
OMB No. 0651-C027 (exp. 5/31/2002)
Tab settings ⇌ ⇌ ⇌ ▼ ▼ ▼ ▼ ▼ ▼

U.S. DEPARTMENT OF COMMERCE
U.S. Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Glen E. Roeters

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No



2. Name and address of receiving party(ies)
Name: DPAC Technologies Corp.
Internal Address: _____

3. Nature of conveyance:
☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: 12/12/01

Street Address: 7321 Lincoln Way
City: Garden Grove State: CA Zip: 92841
Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: 12/12/01
A. Patent Application No.(s)
10016939
B. Patent No.(s)
Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: Mark B. Garred
STETINA BRUNDA GARRED & BRUCKER
Internal Address: _____
12/19/2001 HLE333 00000040 10016939
04 FC:51 40.00 GP
Street Address: 75 Enterprise, Ste. 250
City: Aliso Viejo State: CA Zip: 92656

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 3.41).....\$ 40.00
☒ Enclosed
☐ Authorized to be charged to deposit account
8. Deposit account number:
(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Mark B. Garred [Signature] 12/14/01
Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and documents: 3

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

10/016939
12/14/01

PTO/SB/15 (6-96)

Approved for use through 9/30/98. OMB 0651-0027

Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

ASSIGNMENT OF APPLICATION

Docket Number (Optional):
DENSE-052A

Whereas, I, Glen E. Roeters of Huntington Beach, California, hereafter referred to as applicant, have invented certain new and useful improvements in CSP CHIP STACK WITH FLEX CIRCUIT

☐ for which an application for a United States Patent was filed on _____, Application Number _____/_____.

☒ for which an application for a United States Patent was executed on _____, and

Whereas, DPAC Technologies Corp. of Garden Grove, California, herein referred to as

"assignee" whose post office address is 7321 Lincoln Way, Garden Grove, CA 92841 is desirous of acquiring the entire right, title and interest in the same;

Now, therefore, in consideration of the sum of one dollar (\$1.00), the receipt whereof is acknowledged, and other good and valuable consideration, I, the applicant, by these presents do sell, assign and transfer unto said assignee the full and exclusive right to the said invention in the United States and the entire right, title and interest in and to any and all Patents which may be granted therefor in the United States, I hereby authorize and request the Commissioner of Patents and Trademarks to issue said United States Patent to said assignee, of the entire right, title, and interest in and to the same, for his sole use and behoof, and for the use and behoof of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

Executed this 26th day of November, 2001.

at DPAC Technologies, Garden Grove, CA
Glen E. Roeters
(Signature)

State of Calif. SS: 560-39-8240
County of Orange

Before me personally appeared said _____
and acknowledged the foregoing instrument to be his free act and deed this _____
day of _____, 20____.

Seal

(Notary Public)

PTO/SB/15 (8-96)

Approved for use through 9/30/98. OMB 0651-0027

Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

ASSIGNMENT OF APPLICATION	Docket Number (Optional): DENSE-052A
<p>Whereas, I, <u>Andrew C. Ross</u> of <u>Ramona, California</u>, hereafter referred to as applicant, have invented certain new and useful improvements in <u>A FLEX TAB FOR USE IN STACKING PACKAGED INTEGRATED CIRCUIT CHIPS</u></p> <p><input type="checkbox"/> for which an application for a United States Patent was filed on _____ Application Number _____/_____.</p> <p><input checked="" type="checkbox"/> for which an application for a United States Patent was executed on _____, and</p> <p>Whereas, <u>DPAC Technologies Corp.</u> of <u>Garden Grove, California</u>, herein referred to as "assignee" whose post office address is 7321 Lincoln Way, Garden Grove, CA 92841 is desirous of acquiring the entire right, title and interest in the same;</p> <p>Now, therefore, in consideration of the sum of <u>one</u> dollar (\$1.00), the receipt whereof is acknowledged, and other good and valuable consideration, I, the applicant, by these presents do sell, assign and transfer unto said assignee the full and exclusive right to the said invention in the United States and the entire right, title and interest in and to any and all Patents which may be granted therefor in the United States, I hereby authorize and request the Commissioner of Patents and Trademarks to issue said United States Patent to said assignee, of the entire right, title, and interest in and to the same, for his sole use and behoof, and for the use and behoof of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.</p> <p>Executed this <u>12th</u> day of <u>DECEMBER</u>, 20<u>01</u>.</p> <p>at <u>DPAC TECH, GARDEN GROVE</u></p> <p style="text-align: right;">_____ (Signature)</p> <p>State of <u>CA</u>) SS: <u>624-10-3003</u> County of <u>ORANGE</u> Before me personally appeared said _____ and acknowledged the foregoing instrument to be his free act and deed this _____ day of _____, 20____.</p> <p style="text-align: center;">Seal _____ (Notary Public)</p>	

Express Mail:

(KMS/hms)

Dear Sir:

Please date stamp and return this
card, adding the serial number assigned
where applicable.

Date Mailed: May 28, 2002 Docket No.: DENSE-052A
Serial No.: 10/016,939
Filing Date: December 14, 2001
Title: CSP CHIP STACK WITH FLEX CIRCUIT

Papers transmitted herewith: Transmittal; IDS (in triplicate); form PTO-1449; and
prior art 52 refs.

FROM:

LAW OFFICES

Stetina Brunda Garred & Brucker

PATENT, TRADEMARK, AND COPYRIGHT CAUSES

75 ENTERPRISE, SUITE 250

ALISO VIEJO, CALIFORNIA 92656

TO:

Box DD

Assistant Commissioner for Patents
Washington, D.C. 20231

FIRST CLASS MAIL

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

FEE TRANSMITTAL for FY 2004

Effective 10/01/2003. Patent fees are subject to annual revision.

☐ Applicant claims small entity status. See 37 CFR 1.27

TOTAL AMOUNT OF PAYMENT (\$) 40.00

Complete if Known

Application Number	10/016,939
Filing Date	12/14/2001
First Named Inventor	Glen Roeters
Examiner Name	Cruz, Lourdes
Art Unit	3868
Attorney Docket No.	DPAC-052A

METHOD OF PAYMENT (check all that apply)☐ Check ☐ Credit card ☐ Money Order ☐ Other ☐ None☒ Deposit Account:Deposit
Account
Number
Deposit
Account
Name

50-0897

Andrews Kurth LLP

The Director is authorized to: (check all that apply)

☒ Charge fee(s) indicated below ☒ Credit any overpayments☒ Charge any additional fee(s) or any underpayment of fee(s)☐ Charge fee(s) indicated below, except for the filing fee to the above-identified deposit account.**FEE CALCULATION****1. BASIC FILING FEE**

Large Entity Fee Code (\$)	Small Entity Fee Code (\$)	Fee Description	Fee Paid
1001 770	2001 385	Utility filing fee	
1002 340	2002 170	Design filing fee	
1003 530	2003 265	Plant filing fee	
1004 770	2004 385	Reissue filing fee	
1005 160	2005 80	Provisional filing fee	
SUBTOTAL (1) (\$)			

2. EXTRA CLAIM FEES FOR UTILITY AND REISSUE

Extra Claims Fee from below Fee Paid

Total Claims -20** = X =

Independent Claims -3** = X =

Multiple Dependent =

Large Entity Fee Code (\$)	Small Entity Fee Code (\$)	Fee Description	Fee Paid
1202 18	2202 9	Claims in excess of 20	
1201 86	2201 43	Independent claims in excess of 3	
1203 290	2203 145	Multiple dependent claim, if not paid	
1204 86	2204 43	** Reissue independent claims over original patent	
1205 18	2205 9	** Reissue claims in excess of 20 and over original patent	
SUBTOTAL (2) (\$)			

**or number previously paid, if greater; For Reissues, see above

FEE CALCULATION (continued)**3. ADDITIONAL FEES**

Large Entity Small Entity

Fee Code (\$)	Fee Code (\$)	Fee Description	Fee Paid
1051 130	2051 65	Surcharge - late filing fee or oath	
1052 50	2052 25	Surcharge - late provisional filing fee or cover sheet	
1053 130	1053 130	Non-English specification	
1812 2,520	1812 2,520	For filing a request for <i>ex parte</i> reexamination	
1804 920*	1804 920*	Requesting publication of SIR prior to Examiner action	
1805 1,840*	1805 1,840*	Requesting publication of SIR after Examiner action	
1251 110	2251 55	Extension for reply within first month	
1252 420	2252 210	Extension for reply within second month	
1253 950	2253 475	Extension for reply within third month	
1254 1,480	2254 740	Extension for reply within fourth month	
1255 2,010	2255 1,005	Extension for reply within fifth month	
1401 330	2401 165	Notice of Appeal	
1402 330	2402 165	Filing a brief in support of an appeal	
1403 290	2403 145	Request for oral hearing	
1451 1,510	1451 1,510	Petition to institute a public use proceeding	
1452 110	2452 55	Petition to revive - unavoidable	
1453 1,330	2453 665	Petition to revive - unintentional	
1501 1,330	2501 665	Utility issue fee (or reissue)	
1502 480	2502 240	Design issue fee	
1503 640	2503 320	Plant issue fee	
1460 130	1460 130	Petitions to the Commissioner	
1807 50	1807 50	Processing fee under 37 CFR 1.17(q)	
1806 180	1806 180	Submission of Information Disclosure Stmt	
8021 40	8021 40	Recording each patent assignment per property (times number of properties)	40.00
1809 770	2809 385	Filing a submission after final rejection (37 CFR 1.129(a))	
1810 770	2810 385	For each additional invention to be examined (37 CFR 1.129(b))	
1801 770	2801 385	Request for Continued Examination (RCE)	
1802 900	1802 900	Request for expedited examination of a design application	

Other fee (specify) _____

*Reduced by Basic Filing Fee Paid

SUBTOTAL (3) (\$) 40.00

SUBMITTED BY

(Complete if applicable)

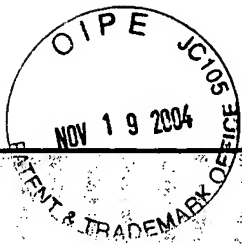
Name (Print/Type)	J. Scott Denko	Registration No. (Attorney/Agent)	37,606	Telephone	512-320-9200
Signature		Date	07/14/2004		

WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.

This collection of information is required by 37 CFR 1.17 and 1.27. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS.

SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.

Form PTO-1619A
Expires 06/30/99
OMB 0651-0027U.S. Department of Commerce
Patent and Trademark OfficeRECORDATION FORM COVER SHEET
PATENTS ONLYTO: THE HONORABLE COMMISSIONER OF PATENTS AND TRADEMARKS: *Please record the attached original document(s) or copy(ies).*

SUBMISSION TYPE

- ☒ New
- ☐ Resubmission (non-recordations)
Document ID # _____
- ☐ Correction of PTO Error
Reel # _____ Frame # _____
- ☐ Corrective Document
Reel # _____ Frame # _____

CONVEYANCE TYPE

- ☒ Assignment
- ☐ Change of Name
- ☐ Security Agreement
- ☐ Merger

Other: _____

CONVEYING PARTY(IES)

Name (line 1): DPAC Technologies Corp.
Name (line 2): (formerly known as Dense-Pac
Name (line 3): Microsystems, Inc.)
Name (line 4):
Name (line 5):
Name (line 6):
Name (line 7):
Execution Date: June 9, 2004
☐ Mark if additional names of conveying parties attached.

RECEIVING PARTY(IES):

Name: Staktek Group L.P.
Address: 8900 Shoal Creek Blvd., Suite 125
City: Austin
State: TX Zip: 78757

☐ If document to be recorded is an assignment and the receiving party is not domiciled in the United States, an appointment of a domestic representative is attached. (*Designation must be a separate document from Assignment.*)

PAGES Enter the total number of pages of the attached conveyance document, including any attachments. 10

APPLICATION NUMBER(S) OR PATENT NUMBER(S) ☐ Mark if additional numbers attached.*Enter either the Patent application number or the patent number (DO NOT ENTER BOTH numbers for the same property)*Patent Application No(s):
10/016,939

Patent No(s):

If this document is being filed together with a new patent application, enter the date the application was signed by the first named executing inventor:

CORRESPONDENT NAME AND ADDRESS

Name: J. Scott Denko
Internal address: Andrews & Kurth LLP
111 Congress Avenue, Suite 1700
Street address: Same
City: Austin
State: Texas Zip: 78701

PATENT COOPERATION TREATY (PCT)

Enter PCT application number
only if a U.S. application number
has not been assigned.

PCT _____
PCT _____
PCT _____

PCT _____
PCT _____
PCT _____

PCT _____
PCT _____
PCT _____

NUMBER OF PROPERTIES

Enter the total number of properties involved: One (1)

FEE AMOUNT

For Amount for Properties Listed (37 CFR 3.41):

\$40.00

Method of Payment:

☐

Enclosed (included in the check covering the filing fee), or

☒

Deposit Account

(Enter for payment by deposit account or if additional fees can be charged to the account.)

☒

Debit Account No.: 50-0897

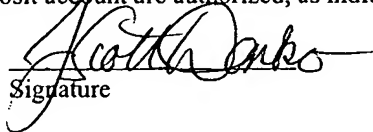
☒

Authorized to charge additional fees or credit any overpayment to Deposit Account
No. 50-0897.

STATEMENT AND SIGNATURE

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Charges to deposit account are authorized, as indicated herein.

J. Scott Denko
Name of Person Signing


Signature

July 14, 2004
Date

06/08/04

EXHIBIT A
ASSIGNMENT OF DPAC ASSETS

WHEREAS, DPAC Technologies Corp. (formerly known as Dense-Pac Microsystems, Inc.) ("DPAC") owns certain intellectual properties consisting of inventions, patents, and patent applications (enumerated on attached and incorporated Exhibit 1) (the "DPAC Assets");

WHEREAS, Staktek Group L.P., a Texas limited partnership, desires to acquire and DPAC desires to assign to Staktek Group L.P., all of DPAC's rights in the DPAC Assets;

NOW, THEREFORE, DPAC, for itself and its predecessors in interest for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, does hereby ASSIGN to Staktek Group L.P., all right, title and interest in the DPAC Assets, this assignment including, but not being limited to:

1. The ASSIGNED INVENTIONS enumerated on Exhibit 1 whether created by DPAC, its predecessors, its legal representatives or its assigns in the United States or any other country or place anywhere in the world;
2. The ASSIGNED PATENTS enumerated on Exhibit 1;
3. The ASSIGNED PATENT APPLICATIONS enumerated on Exhibit 1;
4. All rights of action on account of past, present, and future unauthorized use or infringement of said DPAC Assets including, but not limited to all rights to damages so accrued;
5. The right, where allowed by law, to file in the name of Staktek Group L.P. applications for patent and like protection for any one or more of the DPAC Assets in any country or countries foreign to the United States;
6. All international and domestic rights or priorities associated with any one of the DPAC Assets; and

This Assignment shall be binding upon and shall inure to the benefit of the successors, assigns, and legal representatives of the parties.

06/08/04

EXECUTED on the EFFECTIVE DATE indicated below:

Assignor: DPAC TECHNOLOGIES CORP.

Date: JUNE 9, 2004

By: [Signature]
[DPAC TECHNOLOGIES CORP OFFICER]

Name: CREIGHTON K. EARLY

Title: CHIEF EXECUTIVE OFFICER

THE STATE OF CA]

COUNTY OF Orange]

§
§
§

This instrument was acknowledged by DPAC Officer on this the 9 day of June, 2004.

(Seal)

[Signature]
Notary Public in and for the State of []

My commission expires: 9/25/04

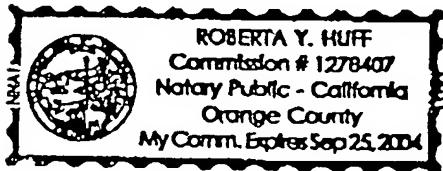


EXHIBIT 1 - DPAC Assets

Updated January 28, 2004

Cue	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required Action
DENSE-002A	Universal Package and Method of Forming the Same	Patent	Original	4/23/1999	09/298,664	4/24/2001	6,222,737	Universal Package and Method of Forming the Same	Issued, 3 1/2 year maintenance fees due 10/24/04.	N/A	None
DENSE-002G	Universal Package and Method of Forming the Same	Patent	Divisional	9/19/2000	09/664,938	3/26/2002	6,360,433	Universal Package and Method of Forming the Same	Issued, 3 1/2 year maintenance fees due 09/26/05.	N/A	None
DENSE-003A	Stackable Chip Package with Flex Carrier	Patent	Original	1/13/2000	09/482,294	7/21/2001	6,262,895	Stackable Chip Package with Flex Carrier	Issued, 3 1/2 year maintenance fees due 01/17/05.	N/A	None
DENSE-003C	Stackable Chip Package with Flex Carrier	Patent	Continuation	4/10/2001	09/838,773	10/29/2002	6,473,308	Stackable Chip Package with Flex Carrier	Issued, 3 1/2 year maintenance fees due 04/29/2006.	N/A	None
DENSE-003A	CSP Stacking Technology Using Rigid/Flex Construction	Patent	Original	3/24/2000	09/535,641	8/20/2002	6,417,433 B1	CSP Stacking Technology Using Rigid/Flex Construction	Issued, 3 1/2 year maintenance fees due 02/20/2006.	PTO	None
DENSE-012A	Mechanically Registered and Interconnected Chip Stack	Patent	Original	6/15/2000	09/594,989			Mechanically Registered and Interconnected Chip Stack	Closed.	N/A	None
DENSE-012G	Mechanically Registered and Attachable Chip Stack	Patent	Divisional	7/24/2002	10/202,185			Mechanically Registered and Attachable Chip Stack	Issued, 3 1/2 year maintenance fee due 12/09/2006	PTO	None
DENSE-013A	Chip Stack and Method of Making Same	Patent	Original	4/13/1995	08/421,801	3/18/1997	5,612,570	Chip Stack and Method of Making Same	Issued, 7 1/2 year maintenance fee due 09/18/2004.	N/A	None
DENSE-013C	Chip Stack and Method of Making Same	Patent	PCT					Chip Stack and Method of Making Same	Closed.	N/A	None
NSB-013A	Modular Panel Stacking Process	Patent	Original	11/17/1997	08/971,499	02/09/1999	5,869,353	Modular Panel Stacking Process	Issued, 7 1/2 year maintenance fee due 08/09/2007.	N/A	None
DENSE-015X	Reinforced Modular Panel Stacking Process	Other	Re-Issue	8/2/2000	09/633,297			Modular Panel Stacking Process	Awaiting Reply re: Non-Recordation of Document	PTO	None
DENSE-016A	IC Chip Package Having Chip Attached to and Wire Bonded within an Overlying Substrate	Patent	Original		07/851,755			IC Chip Package Having Chip Attached to and Wire Bonded within an Overlying Substrate	Closed.	N/A	None

EXHIBIT 1 - DPAC Assets

06/08/04

Updated January 28, 2004

Case	Title/Mark - Invention	Item Type	Patent Trade-mark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required & Owner	Date Required Action Assigned
DENSE-016EP	IC Chip Package and Method of Making the Same	Patent	European		93908306.9			IC Chip Package and Method of Making the Same	Closed.	N/A	None
DENSE-016IP	IC Chip Package and Method of Making the Same	Patent	Japan		5-516611			IC Chip Package and Method of Making the Same	Closed.	N/A	None
DENSE-016PC	IC Chip Package and Method of Making the Same	Patent	PCT	3/10/1993	PCT/US93/02202			IC Chip Package and Method of Making the Same	Closed.	N/A	None
DENSE-016G	IC Chip Package Having Chip Attached to and Wire Bonded within an Overlying Substrate	Patent	Divisional	7/29/1992	07/920,763	5/17/1994	5,313,096	IC Chip Package having Chip Attached to and Wire Bonded within an Overlying Substrate	Issued. 1 1/2 year maintenance fee due 11/17/2005.	N/A	None
DENSE-017A	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Original	5/5/1999	09/305,584	11/27/2001	6,323,060 B1	Stackable Flex Circuit IC Package and Method of Making Same	Issued. 3 1/2 year maintenance fee due 05/27/2005.	N/A	None
DENSE-017EP	Stackable Flex Circuit IC Package and Method of Making Same	Patent	European	10/26/2001	932131.6			Stackable Flex Circuit IC Package and Method of Making the Same	Closed.	FTO	None
DENSE-017HK	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Hong Kong	9/25/2002	1045759			Stackable Flex Circuit IC Package and Method of Making Same	Closed.	FTO	None
DENSE-017JP	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Japan	10/29/2001	2000-616064			Stackable Flex Circuit IC Package and Method of Making the Same	Closed.	DPAC	5/5/2007
DENSE-017KS	Stackable Flex Circuit IC Package and Method of Making Same	Patent	Korea	11/3/2001	2001-7014056			Stackable Flex Circuit IC Package and Method of Making the Same	Closed.	DPAC	5/5/2005
DENSE-017PC	Stackable Flex Circuit IC Package and Method of Making Same	Patent	PCT	5/5/2000	PCT/US00/12393			Stackable Flex Circuit IC Package and Method of Making Same	Closed.	N/A	None
DENSE-017B	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	Continuation-in-Part	5/19/2000	09/574,321	2/26/2002	6,351,029 B1	Flex Wrap Carrier and Method	Issued. 3 1/2 year maintenance fees due 08/26/2005.	N/A	None
DENSE-017BPC	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	PCT	3/29/2001	PCT/US01/10064			Stackable Flex Circuit Chip Package and Method of Making Same	Closed.	N/A	None

AUS353564.4

DPAC
STAKTEK

EXHIBIT 1 - DPAC Assets

06/08/04

Updated: January 28, 2004

Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required Action
DENSE-017B11	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	Taiwan	4/24/2001	90109731			Stackable Flex Circuit Package and Method of Making Same	Closed.	Owner FTO	None
DENSE-017B1	Flex Wrap Carrier and Method	Patent	Continuation-in-Part					Flex Wrap Carrier and Method	Closed, pursuant to client instructions.	N/A	None
DENSE-017BQ	Stackable Flex Circuit Package and Method of Making Same	Patent	Divisional	6/25/2001	09/888,785	7/30/2002	6426240 B1	Stackable Flex Circuit Package and Method of Making Same	Issued, 3 1/2 year maintenance fees due 01/30/2006.	N/A	None
DENSE-017C	Stackable Flex Circuit Chip Package and Method of Making Same	Patent	Continuation	6/25/2001	09/888,792	2/4/2003	6,514,793	Stackable Flex Circuit Chip Package and Method of Making Same	Issued, 3 1/2 year maintenance fees due 08/04/2006.	N/A	None
DENSE-017D	Stackable Flex Circuit and Method of Making Same	Patent	Divisional	11/3/2000	09/706,015	7/30/2002	6,426,549 B1	Stackable Flex Circuit and Method of Making Same	Issued, 3 1/2 year maintenance fees due 01/30/2006.	N/A	None
DENSE-018A	Chip Stack and Method of Making Same	Patent	Original	5/5/1998	09/073,254	1/30/2001	6,180,181 B1	Chip Stack and Method of Making Same	Issued, 3 1/2 year maintenance fees due 07/30/2004.	N/A	None
DENSE-018EP	Chip Stack and Method of Making Same	Patent	European	11/14/2000	99920334.2			Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-018JP	Chip Stack and Method of Making Same	Patent	Japan	10/31/2000	2000-547656			Chip Stack and Method of Making Same	** Closed.	FTO	None
DENSE-018KS	Chip Stack and Method of Making Same	Patent	Korea	11/6/2000	2000-7012384			Chip Stack and Method of Making Same	Closed.	DPAC	5/4/2004
DENSE-018PC	Chip Stack and Method of Making Same	Patent	PCT		PCT/US99/09744			Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-019A	Module and Method of Making Same	Patent	Original					Module and Method of Making Same	Unfiled - Closed.	N/A	None
DENSE-020A	Chip Stack Having Interconnected Bonding Pads on Staggered Edges of Chips	Patent	Original		08/083,092			Chip Stack Having Interconnected Bonding Pads on Staggered Edges of Chips	Closed.	N/A	None

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Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required Action
DENSE-021A	IC Chip Stack and Method of Making	Patent	Original		08/119,518			IC Chip Stack and Method of Making Same	Closed.	Owner	None
DENSE-022A	Memory Module Having Memory Package	Patent	Original		08/083,068			Memory Module Having Memory Package Stages	Closed.	N/A	None
DENSE-023A	Chip Stack and Method of Making Same	Patent	Original		08/935,276			Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-023G	Chip Stack and Method of Making Same	Patent	Divisional		08/097,449			Chip Stack and Method of Making Same	Closed.	N/A	None
DENSE-023A	Externally Configurable Chip Carrier	Patent	Original		07/552,578			Externally Configurable Chip Carrier	Closed.	N/A	None
DENSE-026A	Chip Stack with Active Cooling System	Patent	Original	7/15/2000	09/594,363	5/22/2001	6,236,565 B1	Active Cooling System for Chip Stack	Issued. 3 1/2 year maintenance fees due 11/22/2004.	DPAC	None
DENSE-027A	Chip Stack with Differing Chip Package Types	Patent	Original	7/24/2001	09/912,010	9/30/2003	6,627,984	Frame/Multi-Chip Stacking of Differing Package Types	Issued. 3 1/2 year maintenance fee due 03/20/2007.	DPAC	8/3/2003
DENSE-027G	Chip Stack with Differing Chip Package Types	Patent	Divisional	10/3/2002	10/263,859			Frame/Multi-Chip Stacking of Differing Package Types	** Closed.	PTO	None
DENSE-027HC	Chip Stack with Differing Chip Package Types	Patent	PCT	7/9/2002	PCT/US02/2 1346			Frame/Multi-Chip Stacking of Differing Package Types	** Closed.	DPAC	1/24/2004
DENSE-028A	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Original	6/21/2000	09/598,373	6/11/2002	6,404,043	Panel Stacking of BGA Devices	Issued. 3 1/2 year maintenance fee due 12/11/2005.	N/A	None
DENSE-028B	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Continuation-in-Part					Panel Stacking of BGA Devices	Closed.	N/A	None
DENSE-028B1	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Continuation-in-Part	12/14/2001	10/017,553	5/20/2003	6,566,746	Panel Stacking of BGA Devices	Issued. 3 1/2 year maintenance fees due 11/20/2006.	N/A	None

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Case	Title/Mark - Invention	Item Type	Patent Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required and Owner	Date Required Action Assigned
DENSE-028B10	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Divisional	12/11/2002	10/316,566			Panel Stacking of BGA Devices	** Closed.	PTO	None
DENSE-028G	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Divisional	8/6/2001	09/922,977	4/8/2003	6,344,815	Panel Stacking of BGA Devices to Form 3-D Modules	Issued. 3 1/2 year maintenance fees due 10/08/2006.	w/a	None
DENSE-028GC	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Continuation	11/8/2002	10/230,994			Panel Stacking of BGA Devices to Form 3-D Modules	** Closed.	PTO	None
DENSE-028PC	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	PCT	3/29/2001	PCT/US01/0130			Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Closed.	N/A	None
DENSE-028TI	Panel Stacking of BGA Devices to Form Three-Dimensional Modules	Patent	Taiwan	5/4/2001	90110694			Panel Stacking of BGA Devices to Form Three-Dimensional Modules	** Closed.	DPAC	2/28/2004
DENSE-039A	Flux/Underfill Incorporating Ball Spacers	Patent	Original	6/23/2000	09/602,036			Flux/Underfill Incorporating Ball Spacers	Closed.	N/A	None
DENSE-030A	Module with One Side Stacked Memory	Patent	Original	1/9/2001	09/757,135			Single Density Board with One Side Stack	Closed	N/A	None
DENSE-032A	BGA Device with Flex Flap	Patent	Original					BGA Device with Flex Flap	Closed.	DPAC	None
DENSE-033A	Heterogeneous Enhanced L-P Stack	Patent	Original					Heterogeneous Enhanced LP Stack	** Closed.	DPAC	ASAP
DENSE-034A	Internal Detectors for Capacitive Coupling Test	Patent	Original	4/19/2002	10/126,760			Internal Detectors for Capacitive Coupling Test	Closed.	PTO	None
DENSE-035A	Socketed Stacking	Patent	Original					Socketed Stacking	** Closed	N/A	None
DENSE-037A	3-D Memory Stacking Using Anisotropic Epoxy Interconnection	Patent	Original	4/5/2001	09/826,621	10/29/2002	6,472,735	3-D Memory Stacking Using Anisotropic Epoxy Interconnects	Issued. 3 1/2 year maintenance fees due 04/29/2006.	N/A	None

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Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required	Date Required Action
DENSE-0370	Three-Dimensional Memory Stacking Using Anisotropic Epoxy Interconnects	Patent	Divisional	3/6/2002	10/092,073			3-D Memory Stacking Using Anisotropic Epoxy Interconnects	Closed.	DPAC	9/18/2003
DENSE-043A	Buried Device Stack	Patent	Original					Buried Device Stack	** Closed.	DPAC	ASAP
DENSE-044A	Slice Interconnect Structure	Patent	Original	6/1/2002	10/161,529			Slice Interconnect Structure	Pending; Awaiting Receipt of Response to Restriction Requirement	PTO	none
DENSE-044N	Slice Interconnect Structure	Patent	Provisional	6/15/2001	60/298,432			Slice Interconnect Structure	Utility Application Filed - See DENSE-044N	N/A	None
DENSE-045A	I/O Interface Structure	Patent	Original	1/4/1900	10/160,857			I/O Interface Structure	** Closed.	PTO	None
DENSE-045N	I/O Interface Structure	Patent	Provisional	6/15/2001	60/298,371			I/O Interface Structure	Utility Application Filed - See DENSE-045N	N/A	None
DENSE-046A	Retaining Ring Interconnect Used for 3-D Stacking	Patent	Original	9/20/2001	09/957,373	6/3/2003	6,573,461	Retaining Ring Interconnect Using 3-D Stacking	Issued. 3 1/2 year maintenance fees due 12/03/2006	N/A	None
DENSE-046G	Retaining Ring Interconnect Used for 3-D Stacking	Patent	Divisional	4/8/2002	10/117,836			Retaining Ring Interconnect Using 3-D Stacking	** Closed.	PTO	None
DENSE-047A	Post in a Ring Interconnect Used for 3-D Stacking	Patent	Original	9/20/2001	09/957,190	6/3/2003	6,573,460	Post in Ring Interconnect Using 3-D Stacking	Issued. 3 1/2 year maintenance fees due 12/03/2006	N/A	None
DENSE-047D	Post in a Ring Interconnect Used for 3-D Stacking	Patent	Divisional	4/5/2002	10/117,245			Post in Ring Interconnect Using 3-D Stacking	** Closed.	PTO	None
DENSE-049A	Thermal Ring Used in 3-D Stacking	Patent	Original	11/6/2001	09/994,002			3-D Stacking Using Thermal Ring	** Closed.	PTO	None
DENSE-051A	A Flex Tab for Use in Stacking Packaged Integrated Circuit Chips	Patent	Original	12/17/2001	10/024,389			Flex Tab Stacking	** Closed.	PTO	None

EXHIBIT 1 - DPAC Assets

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Updated: January 28, 2004

Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required of Owner	Date Required Action Assigned
DENSE-052A	CSP Chip Stack with Flex Circuit	Patent	Original	12/14/2001	10/016,939			C-S Stack with Double Sided Flex and Formed Lead	** Closed.	PTO	None
DENSE-053A	Folded Flex Circuit with z-axis Interconnect	Patent	Original					Folded Flex Circuit with z-axis Interconnect	Closed.	DPAC	None
DENSE-053A	CS-STACK	Patent	Original					CS-STACK	Closed.	N/A	None
DENSE-059A	Trench Transposer	Patent	Original	4/7/2003	10/408,517			Trench Transposer	** Closed.	PTO	None
DENSE-060A	Integrated Z-Axis Interconnect on Post Processed Chip Scale Package	Patent	Original					Integrated Z-Axis Interconnect on Post Processed Chip Scale Package	Closed.	DPAC	None
DENSE-061A	Direct Die Scale	Patent	Original					Direct Die Scale	Closed.	DPAC	None
DENSE-062A	Near Die Stack	Patent	Original					Near Die Stack	Closed.	DPAC	None
DENSE-065A	T.S.O.P STACKING USING LASER/SPOT WELDING INTERCONNECT	Patent	Original					T.S.O.P STACKING USING LASER/SPOT WELDING INTERCONNECT	Closed (Combined with DENSE-067A)	N/A	None
DENSE-066A	TSOP STACKING USING UNDERLEAD INTERPOSER	Patent	Original	4/7/2003	10/408,697			TSOP STACKING USING UNDERLEAD INTERPOSER	** Closed.	PTO	None
DENSE-067A	THIN SCALE OUTLINE PACKAGE STACK	Patent	Original	12/5/2002	10/310,368			THIN SCALE OUTLINE PACKAGE STACK	Response to OA due 6/24/04	PTO	6/24/04
DENSE-067B	THIN SCALE OUTLINE PACKAGE STACK	Patent	Continuation-in-Part	7/1/4/03	10/620,157			THIN SCALE OUTLINE PACKAGE STACK	Awaiting Receipt of Response to Restriction Requirement	DPAC	None
DENSE-067S	T.S.O.P. STACK PATENT SEARCH	Patent	Search					T.S.O.P. STACK PATENT SEARCH	Patent Search Opinion Letter to client 12/31/2002.	N/A	None

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Case	Title/Mark - Invention	Item Type	Patent Trademark Type	Filing Date	Serial Number	Issue Date	Patent/ Trademark Registration Number	Description	Status	Action Required by Owner	Date Required Action Assigned
DENSE-068A	T.S.O.P. POLYIMIDE FILM STRIP STACK	Patent	Original					T.S.O.P. POLYIMIDE FILM STRIP STACK	** Closed.	DPAC	None
DENSE-069A	TRANSPOSER CONVERTER FOR MONOLITHIC TO STACKABLE	Patent	Original					TRANSPOSER CONVERTER FOR MONOLITHIC TO STACKABLE	** Closed.	DPAC	None
DENSE-070A	STAIR-STEP SIGNAL ROUTING	Patent	Original	4/21/2003	10/420,485			STAIR-STEP SIGNAL ROUTING	Awaiting Receipt of Final Office Action	PTO	None
DENSE-071N	METHOD TO ACCESS SCALABLE ARRAYS OF MEMORY VIA HYPER TRANSPORT BUSES	Patent	Provisional					METHOD TO ACCESS SCALABLE ARRAYS OF MEMORY VIA HYPER TRANSPORT BUSES	Closed.	N/A	None
DENSE-072A	TSOP STACK ENHANCEMENTS	Patent	Original					TSOP STACK ENHANCEMENTS	Closed.	DPAC	None

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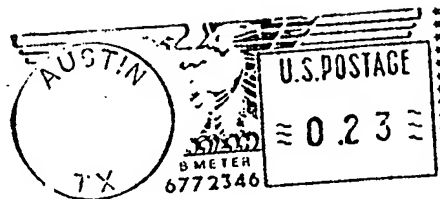
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PATENT

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Applicant: _____ Docket No. DPAC-052A
Assignee: _____ Resp. Atty: _____
Filing Date: 12/14/01 Date Mailed: 7/14/04
Serial No.: 10/016,939 Date Due: _____
Title: _____

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PATENT

Applicant: _____ Docket No. DPAC-052A
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Filing Date: 12/14/01 Date Mailed: 7/14/04
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PATENT

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Applicant: Roetkes Docket No. DPAC-052A
Assignee: Stattek Group, LLP Resp. Atty: S. Scott Decker
Filing Date: 12/14/01 Date Mailed: 7-28-04
Serial No.: 101016, 939 Date Due: JUL 28 2004
Title: CSP Chip Stack with Flex Circuit



- ☒ Transmittal Letter
- ☐ Application PCT ☐ Utility ☐ Conversion ☐ Check No. ☐ for \$
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- ☐ Drawings ☐ pages; Abstract ☐ pages ☐ Petition for
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